

U.S. Department of Commerce, Patent and Trademark Office				Attorney Docket No.: 026-0047	
				Application No.: 10/813,886	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Applicant(s): Ligang Zhang et al.	
(Use several sheets if necessary)				Filing Date: March 31, 2004	
				Group Art Unit: Not yet assigned	
				Date Submitted: April 30, 2004	
U.S. Patent Documents					
*Examiner Initial		Document Number	Date	Name	
JEM	AA	5,083,236	Jan. 21, 1992	Chason et al.	
JEM	AB	5,461,353	Oct. 24, 1995	Eberhardt	
JEM	AC	6,218,729	Apr. 17, 2001	Zavrel, Jr. et al.	
JEM	AD	6,362,525	Mar. 26, 2002	Rahim	
JEM	AE	6,389,691	May 21, 2002	Rinne et al.	
JEM	AG	6,486,534	Nov. 26, 2002	Sridharan et al.	
	AH				
	AI				
	AJ				
	AK				
Foreign Patent Documents					
		Document	Date	Country	Translation
					Yes No
JEM	AL	0 675 539 A2	Oct. 4, 1995	Europe	
JEM	AM	WO 02/067326 A2	Aug. 29, 2002	PCT	
	AN				
	AP				
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)					
	AR	"Unitive - CSP On the Edge", Unitive Inc. 2003 (from website - <a href="http://www.unitive.com/cspedge/index.cfm">http://www.unitive.com/cspedge/index.cfm</a> ), 2 pages.			
	AS	"Unitive Design Guidelines", <a href="http://www.unitive.com">www.unitive.com</a> , 2001, pp. 1-18.			
	AT				
Examiner	J. E. Matlack		Date Considered 3-16-06		
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.					



PTO/SB/08A (Substitute for form 1449/PTO)	Attorney Docket No.: 026-0047
	Application No.: 10/813,886
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>	First Named Inventor: Ligang Zhang
	Filing Date: March 31, 2004
	Group Art Unit: 2811
	Examiner Name: Quang D. Vu
Sheet 1 of 1	Date Submitted: July 13, 2005

[illegible]

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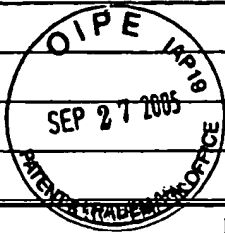
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT		First Named Inventor: Ligang Zhang	
		Filing Date: March 31, 2004	
		Group Art Unit: 2811	
		Examiner Name: Jennifer E. Matisiak	
Sheet 1 of 1		Date Submitted: September 23, 2005	



NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. <sup>1</sup>	Include name of author (In CAPITAL LETTERS), title of article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
JEM	AA	FROMMBERGER, Michael, et al., "Integration of Crossed Anisotropy Magnetic Core Into Toroidal Thin-Film Inductors," IEEE Transactions on Microwave Theory and Techniques, Vol. 53, No. 6, June 2005, pp. 2096-2100.	
JEM	AB	KIM, Sung-Jin, et al., "Realization of High-Q Inductors Using Wirebonding Technology," School of Electronics Engineering, Ajou University, AP-ASIG Proceedings, August 1999, 4 pages.	
JEM	AC	LONG, John R. and Miles A. Copeland, "The Modeling, Characterization, and Design of Monolithic Inductors for Silicon RF ICs," IEEE Journal of Solid-State Circuits, Vol. 32, No. 3, March 1997, pp. 357-369.	
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JEM	AF	TRELEAVEN, Dave and Dick James, "Integrated Circuit Passive Components," Whitepapers, Chipworks, <a href="http://www.chipworks.com/resources/resources_whitepapers.asp">www.chipworks.com/resources/resources_whitepapers.asp</a> , 4 pages.	
JEM	AG	TSUI, Hau-Yiu and Jack Lau, 2003 IEEE MTT-S Digest, pp. 225-228.	
JEM	AH	WU, Joyce H., et al., "A Through-Wafer Interconnect in Silicon for RFICs," IEEE Transactions on Electron Devices, Vol. 51, No. 11, November 2004, pp. 1765-1771.	
JEM	AI	ZANNOTH, Markus, et al., "A Fully Integrated VCO at 2 GHz," IEEE Journal of Solid-State Circuits, Vol. 33, No. 12, December 1998, pp. 1987-1991.	
JEM	AJ	ZOU, Jun, et al., "Development of Vertical Planar Coil Inductors Using Plastic Deformation Magnetic Assembly (PDMA), 2001 IEEE International Microwave Symposium, May 2001, 4 pages.	
Examiner Signature		Jennifer E. Matisiak	Date Considered
			3-16-06

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